

SEMICONDUCTOR DEVICE AND  
METHOD OF MANUFACTURING THE SAME

5                    ABSTRACT OF THE DISCLOSURE

10                    A semiconductor device wherein in formation of  
the wiring connection, an opening is made up to the  
middle of the insulating film, a side wall is formed, a  
burying wiring with the lower portion is arranged, a  
pad is formed, and a pad is formed in a polyplug  
contact without a masking step. Further, a conductive  
material is filled in the hole in the insulating film,  
a hole is opened in this material, a side wall is  
15                    formed on the inner wall, a shrunken contact is opened  
by using this as a mask, and the conductive material is  
filled.